MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet





SMA

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any * Weight: 0.063 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature uniess otherwies specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

TYPE NUMBER		SS215	SS220	UNITS
Maximum Recurrent Peak Reverse Voltage		150	200	V
Maximum RMS Voltage		105	140	V
Maximum DC Blocking Voltage		150	200	V
Maximum Average Forward Rectified Curre	ent			
at T _L =100°C		2.0		А
Peak Forward Surge Current, 8.3 ms single	e half sine-wave			
superimposed on rated load (JEDEC method)		50		А
Maximum Instantaneous Forward Voltage at 2.0A		0.92		V
Maximum DC Reverse Current	Ta=25°C	0.	02	mA
at Rated DC Blocking Voltage	Ta=100°C		2	mA
Typical Junction Capacitance (Note1)		170		PF
Typical Thermal Resistance RθJL (Note 2)		12		°C/W
Operating Temperature Range T _J		-65 — +150		°C
Storage Temperature Range Tsтв		-65 + 150		°C

NOTES:

- 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
- 2. Thermal Resistance Junction to Lead Vertical PC Board Mounting 0.375"(9.5mm) Lead Length.

SS215 THRU SS220 HF





RATING AND CHARACTERISTIC CURVES (SS215 THRU SS220)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

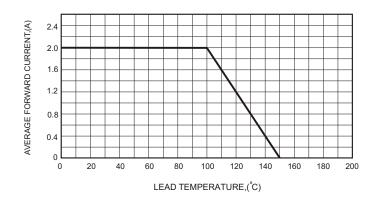


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

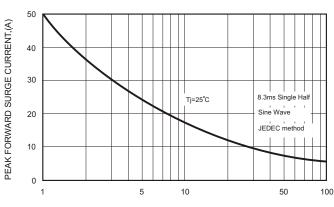


FIG.4-TYPICAL JUNCTION CAPACITANCE

NUMBER OF CYCLES AT 60Hz

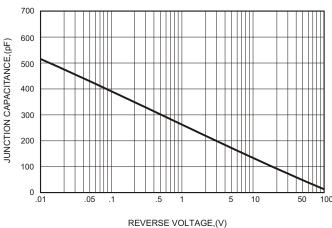


FIG.2-TYPICAL FORWARD

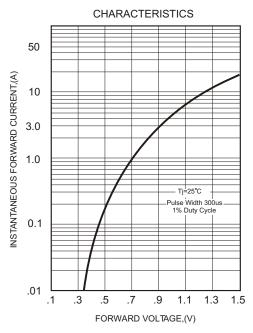
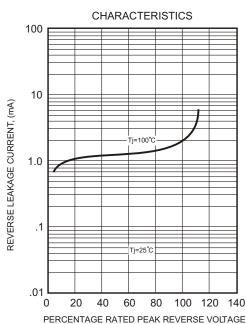
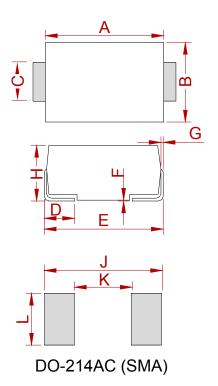


FIG.5 - TYPICAL REVERSE





PACKAGE MECHANICAL DATA



		Dimensions				
Ref.	Millimeters		Inches			
	Min.	Max.	Min.	Max.		
Α	4.25	4.65	0.167	0.183		
В	2.50	2.90	0.098	0.114		
С	1.35	1.65	0.053	0.065		
D	0.76	1.52	0.030	0.060		
Ε	4.93	5.28	0.194	0.208		
F	0.051	0.203	0.002	0.008		
G	0.15	0.31	0.006	0.012		
Н	1.98	2.41	0.078	0.095		
J	6.50		0.256			
K		2.30		0.090		
L	1.70		0.067			

REEL SPECIFICATION

P/N	PKG	QTY
SS215 THRU SS220	SMA	2000



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